Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1.-28. (Canceled)

29. (Currently Amended) A ceramic heater for heating a wafer, comprising a disk-shaped ceramic sintered substrate and a heat generation pattern formed in an interior of the ceramic sintered substrate; a part of the heat generation pattern being displaced on an offset level different from others of said heat generation pattern in a thickness direction of said ceramic sintered substrate; ~~and~~ a maximum amount of offset displacement in said heat generation pattern being in a range of 5 to 2000 μm; and the heat generation pattern not overlapping itself in a contacting manner.

30. (Previously Presented) A ceramic heater according to claim 29, wherein said heat generation pattern is flat at a cross-section in the thickness direction of said ceramic sintered substrate.

31. (Currently Amended) A ceramic heater according to claim 29, wherein said heat generation pattern comprises at least one spiral wire ~~bodies.~~body.

32. (Previously Presented) A ceramic heater according to claim 29, wherein an amount of offset displacement between mutually adjacent portions in said heat generation patterns is in a range of 1 to 100 μm.

33. (Previously Presented) A ceramic heater according to claim 29, wherein said maximum amount of offset displacement is in a range of 3 to 500 μm.

34. (Previously Presented) A ceramic heater according to claim 29, wherein said maximum amount of offset displacement is in a range of 40 to 500 μm.

35. (Previously Presented) A ceramic heater according to claim 29, wherein said ceramic sintered substrate is made of a nitride ceramic or a carbide ceramic.

36. (Previously Presented) A ceramic heater according to claim 29, wherein said ceramic sintered substrate has an anti-thermal shock property ΔT of 190 to 200°C.

37. (Previously Presented) A ceramic heater according to claim 29, wherein said heat generation pattern is flat at a cross-section in the thickness direction of said ceramic sintered substrate and has a thickness of 5 to 50 μm.

38. (Currently Amended) A ceramic heater according to claim 29, wherein said heat generation pattern comprises one or more spiral wire bodies each having a thickness of 0.1 to 2 mm.

39. (Currently Amended) A ceramic heater according to claim 29, wherein said heat generation pattern comprises one or more spiral wire bodies each having a width of 1 to 10 mm.

40. (Currently Amended) A ceramic heater according to claim 29, wherein said heat generation pattern comprises one or more spiral wire bodies each having an aspect ratio (width/thickness) of 1 to 10.